



Material Content Data Sheet



Sales Product Name		ESD113-B1-02ELS E6327		Issued		19. July 2018		
MA#		MA001085750						
Package		PG-TSSLP-2-4		Weight*		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.33		3262	
	noble metal	gold	7440-57-5	0.003	1.27		12661	
	inorganic material	silicon	7440-21-3	0.020	9.38	10.98	93810	109733
leadframe	non noble metal	nickel	7440-02-0	0.108	50.59	50.59	505908	505908
wire	noble metal	gold	7440-57-5	0.003	1.47	1.47	14748	14748
encapsulation	organic material	carbon black	1333-86-4	0.000	0.16		1633	
	plastics	epoxy resin	-	0.010	4.74		47432	
	inorganic material	silicondioxide	60676-86-0	0.059	27.80	32.70	278047	327112
leadfinish	noble metal	gold	7440-57-5	0.004	1.73	1.73	17262	17262
plating	noble metal	palladium	7440-05-3	0.001	0.60		5986	
	noble metal	gold	7440-57-5	0.004	1.93	2.53	19251	25237
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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